*** Material Composition - nRF51422**

Material	Purpose	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogenous material	PPM	% weight of substance per package
Polybenzoxazole1	Dielectric	Polyamide & Gamma-butyrolactone (75~95%)	----------	0.100198	100	8351	0.835%
Polybenzoxazole2	Dielectric		----------	0.095804	100	7985	0.798%
RDL Seed Layer	Seed Layer	Ti	7440-32-6	0.000305	3.93	25	0.003%
	Seed Layer	W	7440-33-7	0.002743	35.40	229	0.023%
	Seed Layer	Cu	7440-50-8	0.004701	60.67	392	0.039%
RDL Copper	Interconnect	Cu	7440-50-8	0.094023	100	7836	0.784%
UBM Seed Layer	UBM	Ti	7440-32-6	0.000135	3.93	11	0.001%
	UBM	W	7440-33-7	0.001214	35.40	101	0.010%
	UBM	Cu	7440-50-8	0.002081	60.67	173	0.017%
UBM Copper	UBM	Cu	7440-50-8	0.093638	100	7804	0.780%
Solder Ball	Interconnect	Sn	7440-31-5	1.361830	95.5	113502	11.350%
	Interconnect	Ag	7440-22-4	0.057040	4.0	4754	0.475%
	Interconnect	Cu	7440-50-8	0.007130	0.5	594	0.059%
Die	Circuit	Si	7440-21-3	9.687656	100	807418	80.742%
Top Surface Laminate	Mark Surface	Silica,Epoxy resin	----------	0.489815	100	40824	4.082%
			Package Weight (mg):	**12.00**		**% Total:**	**100.00%**